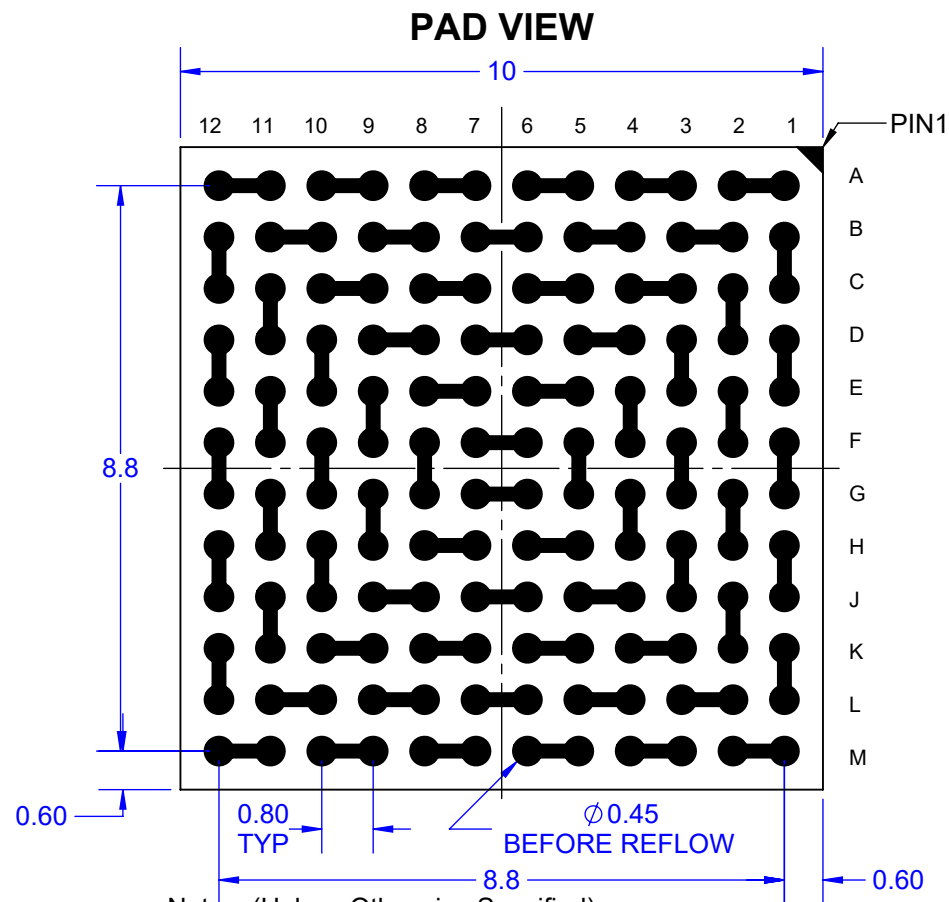



SECTION A-A
SCALE 8.5 : 1

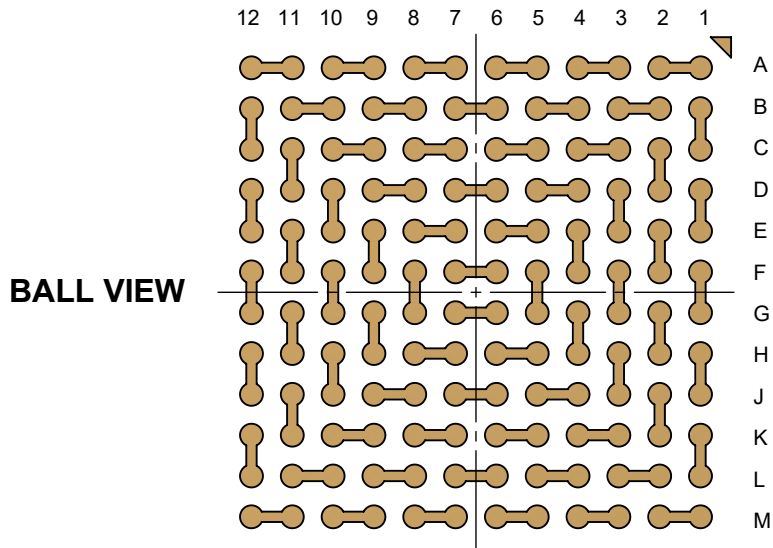


Notes: (Unless Otherwise Specified).

1. DIMENSIONS: MM.
2. SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
3. BALL DIAMETER (BEFORE REFLOW): 0.45mm (18 mil).
4. SOLDER MASK DEFINED PAD OPENING: 0.36mm (14 mil).
5. PAD MATERIAL: PAD Cu DIAMETER 0.61mm (24mil).
6. SUBSTRATE MATERIAL: BT.
7. DUMMY DIE: SIZE OPTIONAL.
8. DAISY CHAIN PATTERN (SEE PAGE 2).
9. MSL-3 RECOMMEND BAKING 24 HOURS @125°C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD

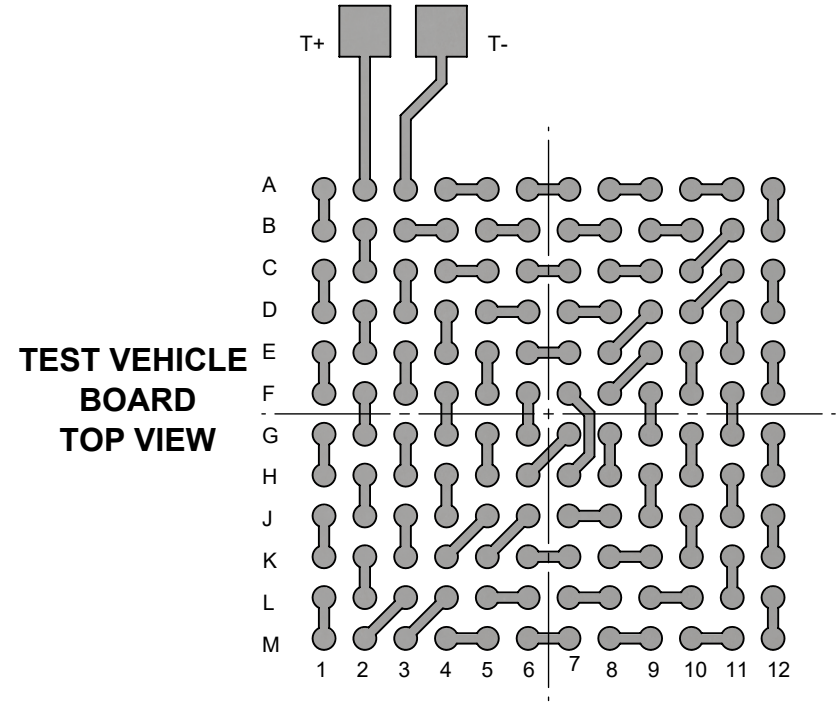
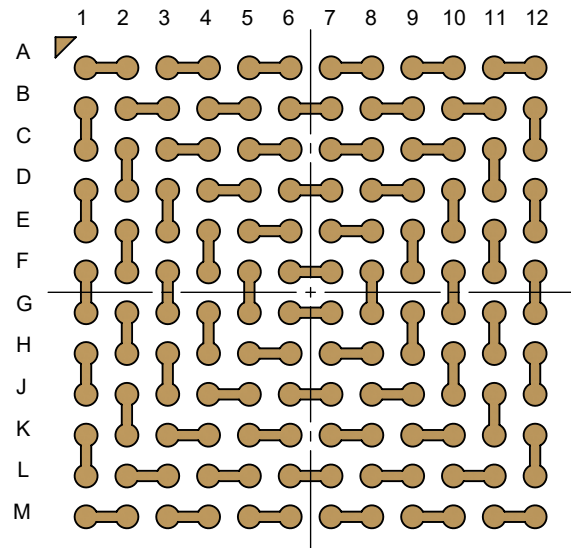
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
CSP144T.8C-DC128D	SAC305	YES	YES	YES
CSP144T.8-DC128D	SnPb	NO	NO	YES

APPROVALS	DATE				
DRAWN T. Au	01/10/2022				
ENG M. Hart	01/10/2022	TITLE CSP144T.8C-DC128D DAISY CHAIN CSP/BGA			
MFG		SCALE 7:1	SIZE A	DRAWING NO. 581284	REV A
REVISD		DO NOT SCALE DRAWING			SHEET 1 OF 3



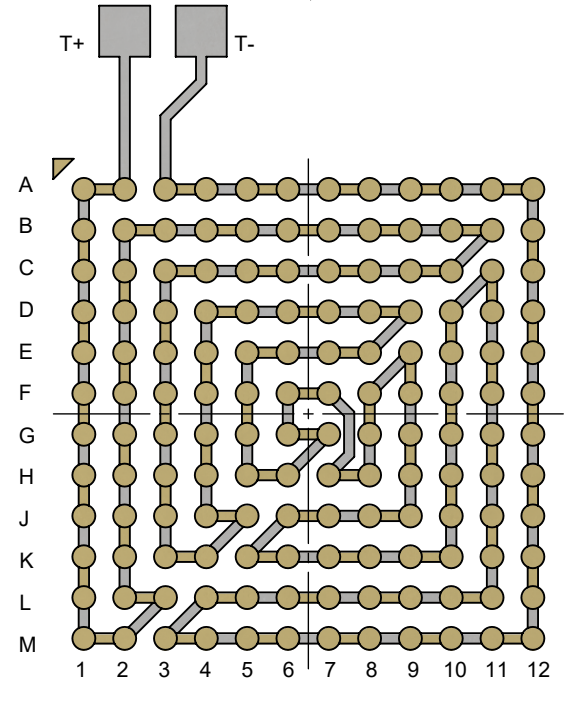
BALL VIEW

**BOTTOM SIDE
(TOP X-RAY VIEW)**



**TEST VEHICLE
BOARD
TOP VIEW**

**AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)**

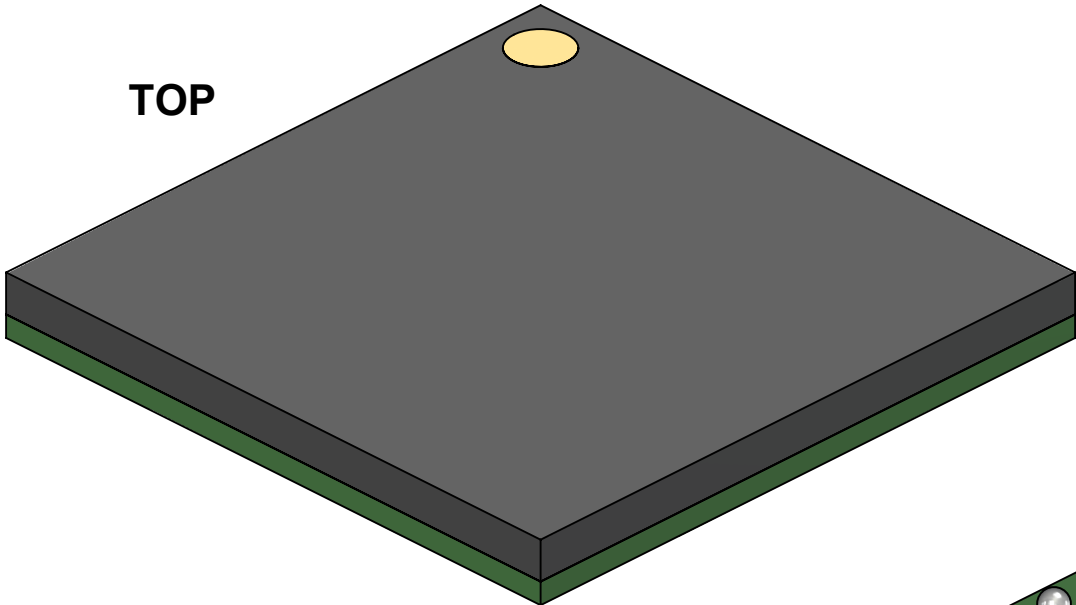


- NOTES:
1. PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 2. PCB Cu BALL PAD DIAMETER: 0.61mm (24 mil).
 3. PCB DAISY CHAIN TRACING LINE WIDTH: 0.203mm (8 mil).
 4. SMD (SOLDER MASK DEFINED) PAD OPENING: \varnothing 0.36mm (14 mil).

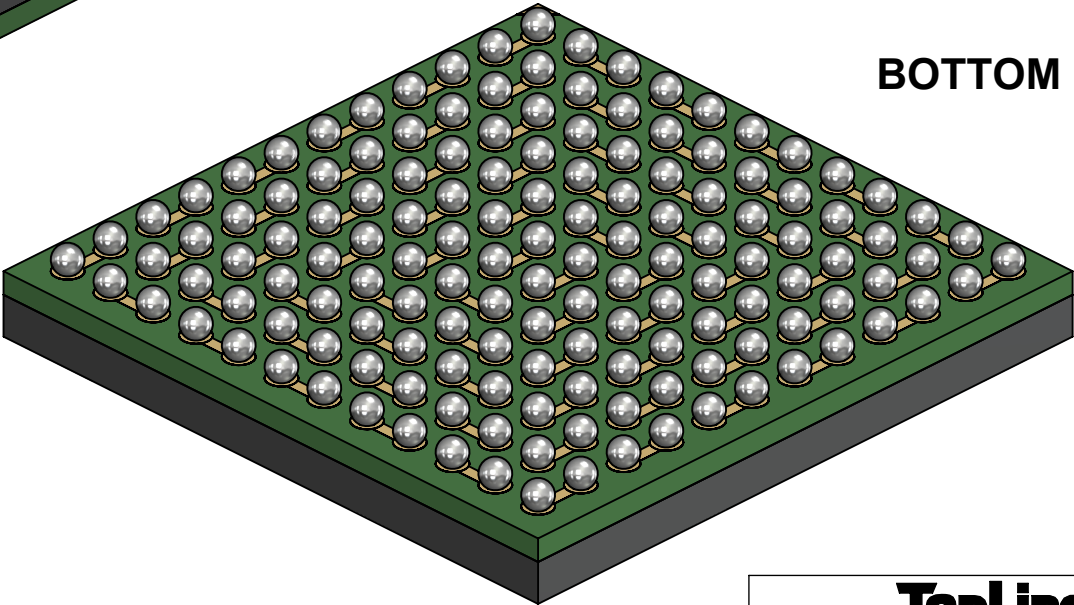
TopLine[®]			
TITLE		CSP144T.8C-DC128D DAISY CHAIN CSP/BGA	
SCALE	SIZE	DRAWING NO.	REV
5.5:1	A	581284	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

**MODEL
WITH SOLDER BALLS**

TOP



BOTTOM



TopLine[®]

TITLE CSP144T.8C-DC128D
DAISY CHAIN CSP/BGA

SCALE 8:1	SIZE A	DRAWING NO. 581284	REV A
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DO NOT SCALE DRAWING SHEET 3 OF 3